Document Number: MHL9838N

Rev. 7, 8/2006

Cellular Band RF Linear LDMOS Amplifier

Designed for ultra-linear amplifier applications in 50 ohm systems operating in the cellular frequency band. A silicon FET Class A design provides outstanding linearity and gain. In addition, the excellent group delay and phase linearity characteristics are ideal for the most demanding analog or digital modulation systems, such as TDMA and CDMA.

- Third Order Intercept: 50 dBm Typ
- Power Gain: 31 dB Typ (@ f = 880 MHz)
- Input and Output VSWR ≤ 1.5:1

Features

- Excellent Phase Linearity and Group Delay Characteristics
- Ideal for Feedforward Base Station Applications
- For Use in TDMA and CDMA Multi-Carrier Applications
- N Suffix Indicates Lead-Free Terminations

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800 - 925 MHz 8.0 W, 31 dB RF LINEAR LDMOS AMPLIFIER

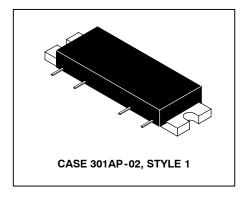


Table 1. Absolute Maximum Ratings (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DC Supply Voltage	V_{DD}	30	Vdc
RF Input Power	P _{in}	+6	dBm
Storage Temperature Range	T _{stg}	- 40 to +100	°C
Operating Case Temperature Range	T _C	- 20 to +100	°C

Table 2. Electrical Characteristics (V_{DD} = 28 Vdc, T_{C} = 25°C; 50 Ω System)

Characteristic	Symbol	Min	Тур	Max	Unit	
Supply Current		I _{DD}	_	770	800	mA
Power Gain	(f = 880 MHz)	G _p	29.5	31	32.5	dB
Gain Flatness	(f = 800 - 925 MHz)	G _F	_	0.1	0.3	dB
Power Output @ 1 dB Compression	(f = 880 MHz)	P1dB	_	39	_	dBm
Third Order Intercept (f1 = 879 MHz, f2 = 884 MHz)		ITO	49	50	_	dBm
Noise Figure	(f = 925 MHz)	NF	_	3.7	4.5	dB

NOTE - <u>CAUTION</u> - MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.



TYPICAL CHARACTERISTICS

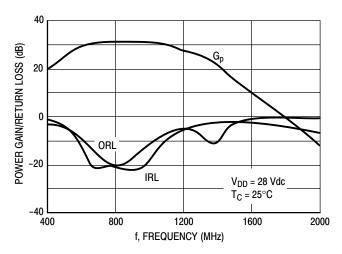


Figure 1. Power Gain, Input Return Loss, Output Return Loss versus Frequency

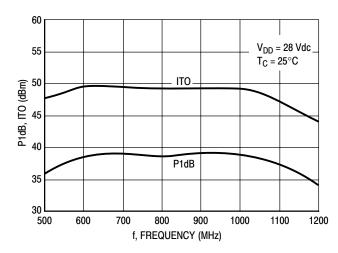


Figure 2. P1dB, ITO versus Frequency

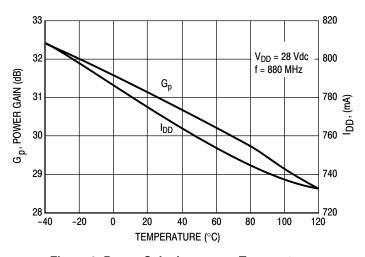


Figure 3. Power Gain, I_{DD} versus Temperature

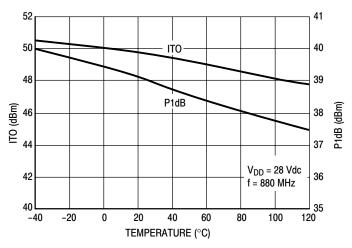


Figure 4. ITO, P1dB versus Temperature

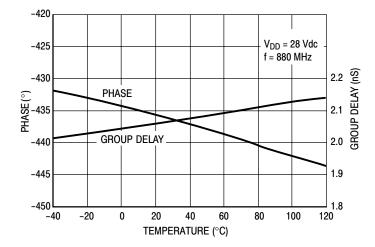


Figure 5. Phase⁽¹⁾, Group Delay⁽¹⁾ versus Temperature

1. In Production Test Fixture

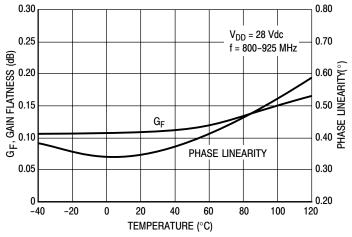


Figure 6. Gain Flatness, Phase Linearity versus Temperature

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TYPICAL CHARACTERISTICS

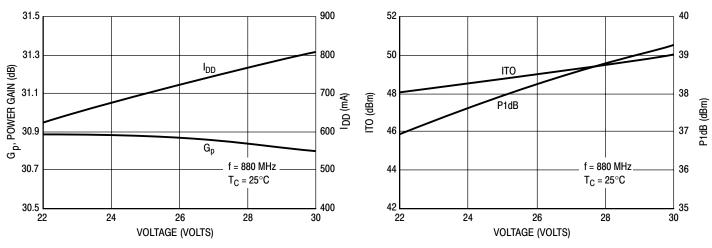


Figure 7. Power Gain, I_{DD} versus Voltage

Figure 8. ITO, P1dB versus Voltage

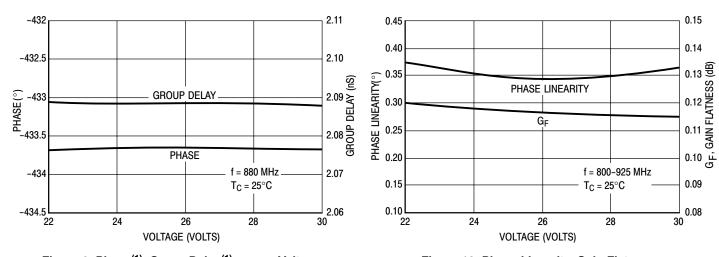
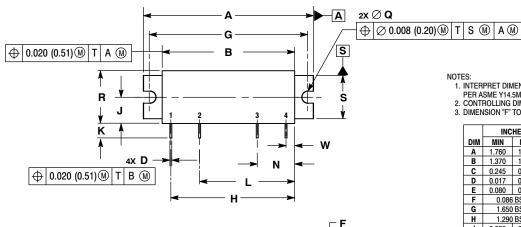


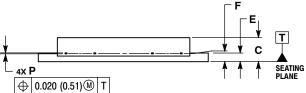
Figure 9. Phase⁽¹⁾, Group Delay⁽¹⁾ versus Voltage

1. In Production Test Fixture

Figure 10. Phase Linearity, Gain Flatness versus Voltage

PACKAGE DIMENSIONS





- NOTES:
 1. INTERPRET DIMENSIONS AND TOLERANCES
 PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION "F" TO CENTER OF LEADS.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.760	1.780	44.70	45.21	
В	1.370	1.390	34.80	35.31	
С	0.245	0.265	6.22	6.73	
D	0.017	0.023	0.43	0.58	
E	0.080	0.100	2.03	2.54	
F	0.086	BSC	2.18 BSC		
G	1.650	BSC	41.91 BSC		
Н	1.290 BSC		32.77 BSC		
J	0.266	0.280	6.76	7.11	
K	0.125	0.165	3.18	4.19	
L	0.990 BSC		25.15 BSC		
N	0.390	BSC	9.91	BSC	
P	0.008	0.013	0.20	0.33	
Q	0.118	0.132	3.00	3.35	
R	0.535	0.555	13.59	14.10	
S	0.445	0.465	11.30	11.81	
W	0.090	BSC	2.29 BSC		

STYLE 1:
PIN 1. RF INPUT
2. VDD1
3. VDD2
4. RF OUTPUT
CASE: GROUND

CASE 301AP-02 ISSUE E

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor Technical Information Center, CH370 1300 N. Alma School Road Chandler, Arizona 85224 +1-800-521-6274 or +1-480-768-2130 support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH Technical Information Center Schatzbogen 7 81829 Muenchen, Germany +44 1296 380 456 (English) +46 8 52200080 (English) +49 89 92103 559 (German) +33 1 69 35 48 48 (French) support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd. Headquarters ARCO Tower 15F 1-8-1, Shimo-Meguro, Meguro-ku, Tokyo 153-0064 Japan 0120 191014 or +81 3 5437 9125 support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd. Technical Information Center 2 Dai King Street Tai Po Industrial Estate Tai Po, N.T., Hong Kong +800 2666 8080 support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center P.O. Box 5405
Denver, Colorado 80217
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